

## **HAT1020R**

# Silicon P Channel Power MOS FET High Speed Power Switching

REJ03G1143-1000

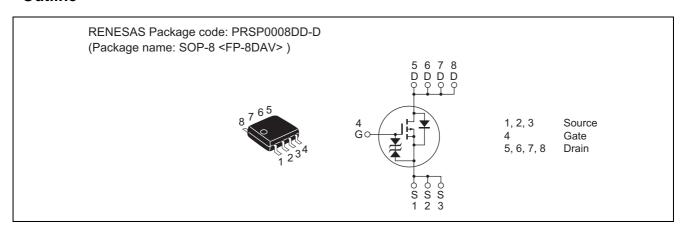
(Previous: ADE-208-435H)

Rev.10.00 Sep 07, 2005

#### **Features**

- Low on-resistance
- Capable of 4 V gate drive
- Low drive current
- High density mounting

#### **Outline**



## **Absolute Maximum Ratings**

 $(Ta = 25^{\circ}C)$ 

Item	Symbol	Value	Unit
Drain to source voltage	$V_{DSS}$	-30	V
Gate to source voltage	$V_{GSS}$	±20	V
Drain current	I <sub>D</sub>	-5	Α
Drain peak current	I <sub>D (pulse)</sub> Note 1	-40	Α
Body-drain diode reverse drain current	I <sub>DR</sub>	-5	Α
Channel dissipation	Pch Note 2	2.5	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW  $\leq$  10  $\mu$ s, duty cycle  $\leq$  1%

2. When using the glass epoxy board (FR4  $40\times40\times1.6$  mm), PW  $\leq10$  s

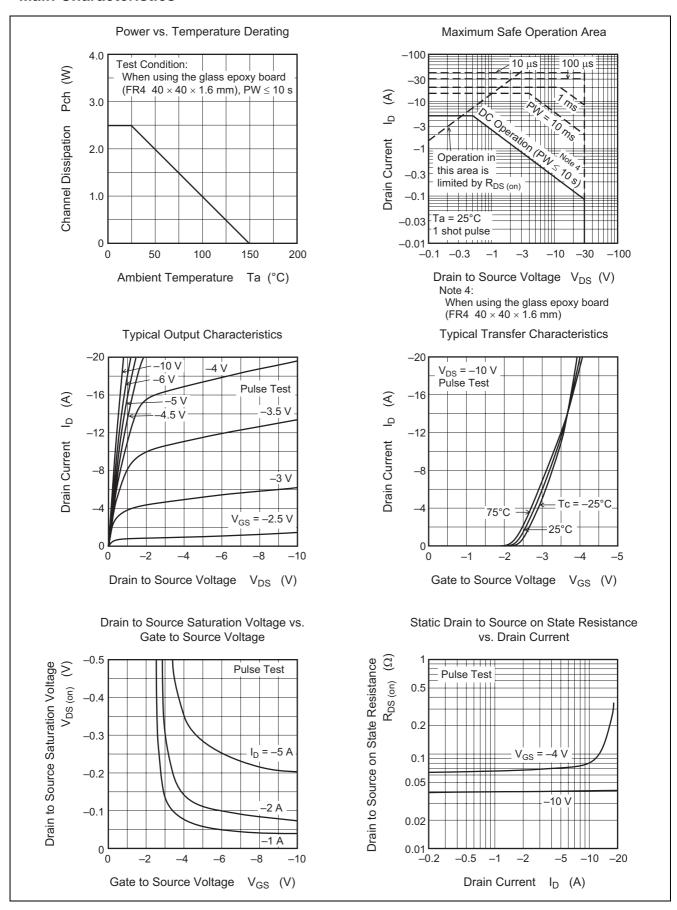
## **Electrical Characteristics**

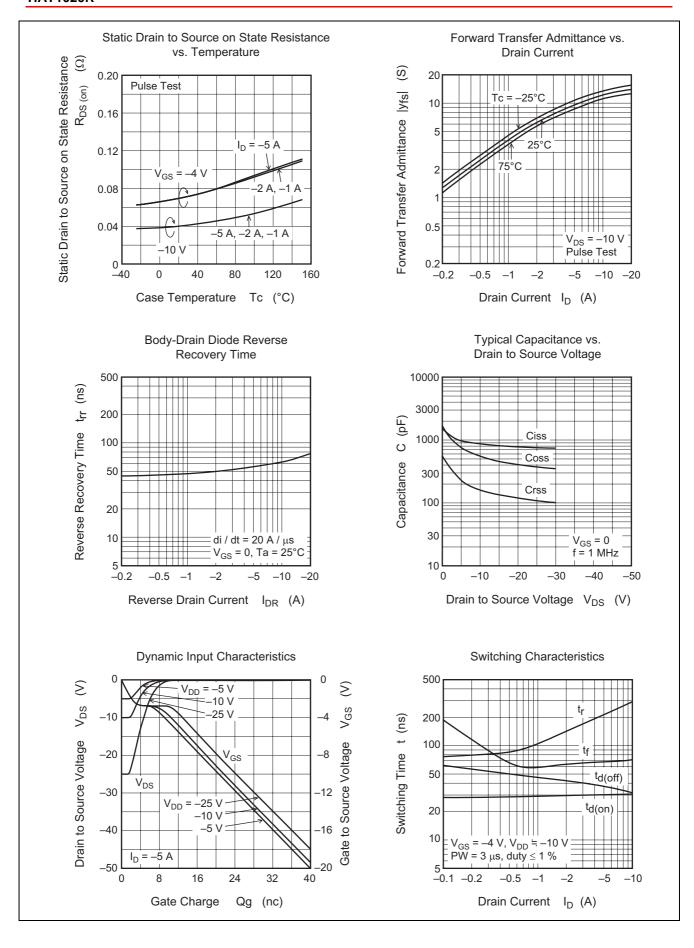
 $(Ta = 25^{\circ}C)$ 

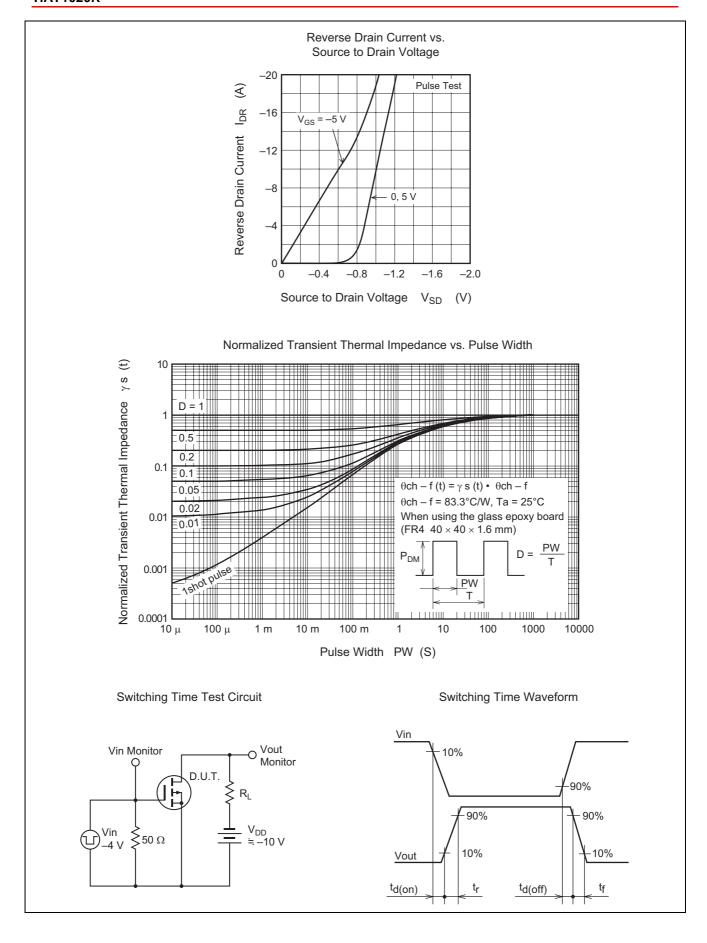
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	V <sub>(BR) DSS</sub>	-30	_	_	V	$I_D = -10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	V <sub>(BR) GSS</sub>	±20	_	_	V	$I_G = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak current	I <sub>GSS</sub>	_	_	±10	μΑ	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I <sub>DSS</sub>	_	_	-10	μΑ	$V_{DS} = -30 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	V <sub>GS (off)</sub>	-1.0	_	-2.5	V	$V_{DS} = -10 \text{ V}, I_D = -1 \text{ mA}$
Static drain to source on state resistance	R <sub>DS (on)</sub>	_	0.04	0.07	Ω	$I_D = -3 \text{ A}, V_{GS} = -10 \text{ V}^{\text{Note } 3}$
	R <sub>DS (on)</sub>	_	0.07	0.13	Ω	$I_D = -3 \text{ A}, V_{GS} = -4 \text{ V}^{\text{Note 3}}$
Forward transfer admittance	y <sub>fs</sub>	5.0	7.5	_	S	$I_D = -3 \text{ A}, V_{DS} = -10 \text{ V}^{\text{Note } 3}$
Input capacitance	Ciss	_	860	_	pF	$V_{DS} = -10 \text{ V}$
Output capacitance	Coss	_	560	_	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	_	165	_	pF	f = 1 MHz
Turn-on delay time	t <sub>d (on)</sub>	_	30	_	ns	$V_{GS} = -4 \text{ V}, I_D = -3 \text{ A},$
Rise time	t <sub>r</sub>	_	170	_	ns	$V_{DD} \cong -10 \text{ V}$
Turn-off delay time	t <sub>d (off)</sub>	_	40	_	ns	
Fall time	t <sub>f</sub>	_	65	_	ns	
Body-drain diode forward voltage	$V_{DF}$	_	-0.9	-1.4	V	$I_F = -5 \text{ A}, V_{GS} = 0^{\text{Note 3}}$
Body-drain diode reverse recovery time	t <sub>rr</sub>	_	55	_	ns	$I_F = -5 \text{ A}, V_{GS} = 0$
						$di_F/dt = 20 A/\mu s$

Note: 3. Pulse test

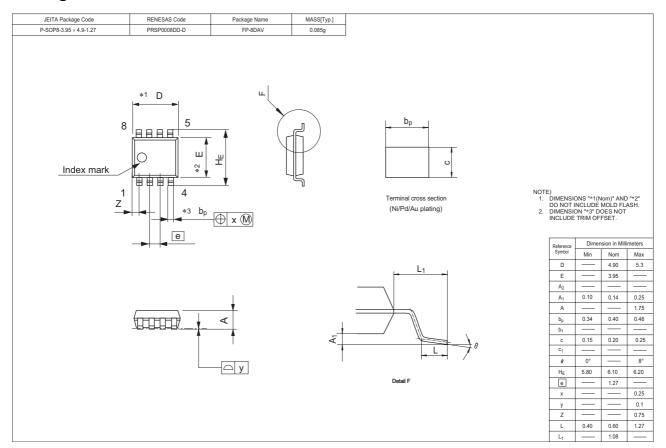
#### **Main Characteristics**







### **Package Dimensions**



## **Ordering Information**

Part Name	Quantity	Shipping Container
HAT1020R-EL-E	2500 pcs	Taping

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